(Patent Document 2) JP-A 2004-27177

(Patent Document 3) JP-A 2006-282783

(Patent Document 4) JP-A 9-176368

SUMMARY

In a first aspect of the present disclosure, there is provided a heat conductivity improving agent comprising a magnesium hydroxide particle having a thickness of 10 nm to 0.2 μm and an aspect ratio (long diameter/thickness) measured by a SEM method of not less than 10.

In a second aspect of the present disclosure, there is provided a heat dissipation agent comprising the disclosed heat conductivity improving agent as an effective component.

In a third aspect of the present disclosure, there is provided a resin composition comprising (i) 100 parts by weight of a resin and (ii) 20 to 300 parts by weight of a heat conductivity improving agent which is a magnesium hydroxide particle having a thickness of 10 nm to 0.2 μm and an aspect ratio (long diameter/thickness) measured by a SEM method of not less than 10.

In a fourth aspect of the present disclosure, there is provided a molded article formed from the disclosed resin composition.

In a fifth aspect of the present disclosure, there is provided a heat radiation sheet formed from the disclosed resin composition.

In a sixth aspect of the present disclosure, there is provided a method of improving the heat conductivity of a resin composition comprising a resin and a magnesium hydroxide particle, comprising mixing 100 parts by weight of the resin with 20 to 300 parts by weight of the magnesium hydroxide particle having a thickness of 10 nm to 0.2 μm and an aspect ratio (long diameter/thickness) measured by a SEM method of not less than 10.

DISCLOSURE OF THE INVENTION

It is an object of the present invention to provide a heat conductivity improving agent capable of improving the heat conductivity of a resin. It is another object of the present invention to provide a resin composition having excellent mechanical strength such as tensile strength and elongation and high heat conductivity as well as a molded article obtained therefrom. It is still another object of the present invention to provide a method for improving the heat conductivity of a resin composition.

The inventors of the present invention conducted studies on the improvement of a heat conductivity improving agent comprising a magnesium hydroxide particle as an effective component. As a result, they found that a magnesium hydroxide particle having a high aspect ratio has an excellent effect as a heat conductivity improving agent. The present invention was accomplished based on this finding.

That is, the present invention is a heat conductivity improving agent which comprises a magnesium hydroxide particle as an effective component, having a thickness of 10 nm to 0.2 μm and an aspect ratio (long diameter/thickness) measured by a SEM method of not less than 10.

Further, the invention is the above resin composition comprising (i) 100 parts by weight of a resin and (ii) 20 to 300 parts by weight of a heat conductivity improving agent which is a magnesium hydroxide particle having a thickness of 10 nm to 0.2 μm and an aspect ratio (long diameter/thickness) measured by a SEM method of not less than 10.

The present invention is also a molded article of the